

Title (en)
VERTICALLY STACKABLE SOCKETS FOR CHIP MODULES

Title (de)
VERTIKAL STAPELBARE FASSUNGSANORDNUNG FÜR INTEGRIERTE SCHALTUNGS-MODULE

Title (fr)
SUPPORTS POUVANT ÊTRE EMPILÉS VERTICALEMENT POUR DES MODULES DE PUCES

Publication
EP 2457291 B1 20160323 (EN)

Application
EP 10701050 A 20100107

Priority
• US 50580809 A 20090720
• US 2010020307 W 20100107

Abstract (en)
[origin: US2011014802A1] The socket system comprises a set of vertically-stackable sockets. A first socket mounts on a printed circuit board to receive a first chip module, and a second socket stacks on the first socket to receive a second chip module. The first socket includes a first set of embedded contacts to electrically connect the first chip module to the printed circuit board, and a second set of embedded contacts to electrically connect the second socket to the printed circuit board. The second socket includes a third set of embedded contacts to electrically connect the second chip module to the printed circuit board. System upgrades are enabled by replacing the chip modules.

IPC 8 full level
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CPC (source: EP US)
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C-Set (source: EP US)
H01L 2924/0002 + H01L 2924/00

Citation (examination)
• US 4437718 A 19840320 - SELINKO GEORGE J [US]
• US 3593064 A 19710713 - WAGNER HORST, et al
• WO 0251224 A2 20020627 - SYNERGESTIC COMPUTING SYSTEMS [DK], et al

Designated contracting state (EPC)
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO SE SI SK SM TR

DOCDB simple family (publication)
US 2011014802 A1 20110120; US 7922523 B2 20110412; CN 102474036 A 20120523; CN 102474036 B 20140430; EP 2457291 A1 20120530; EP 2457291 B1 20160323; WO 2011011096 A1 20110127

DOCDB simple family (application)
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